



Material Content Data Sheet



Sales Product Name				IAUC120N04S6L009		Issued		30. July 2019	
MA#				MA003587320					
Package				PG-TDSON-8-34		Weight*		113.57 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.124	1.87	1.87	18703	18703	
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		140		
	non noble metal	iron	7439-89-6	0.053	0.05		466		
	non noble metal	copper	7440-50-8	52.842	46.55	46.61	465276	465882	
	noble metal	gold	7440-57-5	0.042	0.04	0.04	370	370	
wire	noble metal	gold	7440-57-5	0.042	0.04	0.04	370	370	
encapsulation	organic material	carbon black	1333-86-4	0.073	0.06		645		
	plastics	epoxy resin	-	5.785	5.09		50942		
	inorganic material	silicondioxide	60676-86-0	30.758	27.08	32.23	270829	322416	
leadfinish	non noble metal	tin	7440-31-5	1.574	1.39	1.39	13857	13857	
plating	noble metal	silver	7440-22-4	0.209	0.18	0.18	1842	1842	
solder	non noble metal	tin	7440-31-5	0.046	0.04		404		
	noble metal	silver	7440-22-4	0.057	0.05		505		
	non noble metal	lead	7439-92-1	2.192	1.93	2.02	19304	20213	
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005	0.00		45		
	non noble metal	iron	7439-89-6	0.017	0.01		148		
	non noble metal	copper	7440-50-8	16.828	14.82	14.83	148168	148361	
clip plating	noble metal	silver	7440-22-4	0.639	0.56	0.56	5626	5626	
heatspreader	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	iron	7439-89-6	0.000	0.00		3		
	non noble metal	copper	7440-50-8	0.310	0.27	0.27	2726	2730	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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